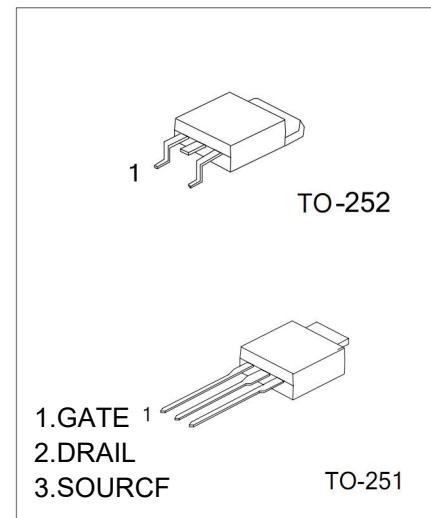




SHENZHEN MENGKE ELECTRONICS TECHNOLOGY CO.,LTD

TO-252/251 Plastic-Encapsulate MOSFETS**MKD407P P-Channel 60-V(D-S) Power MOSFET**

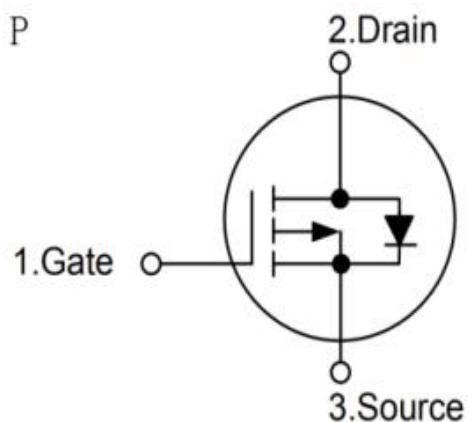
V(BR)DSS	RDS(on)MAX	ID
-60 V	115mΩ@ 10 V	-12A
	150mΩ@ 4.5 V	

Equivalent Circuit:**General Description:**

The MKD407 uses advanced trench technology to provide excellent RDS(ON), low gate charge and low gate resistance. With the excellent thermal resistance of the DPAK package, this device is well suited for high current load applications.

FEATURE:

- ※ Low capacitance
- ※ Low gate charge
- ※ Fast switching capability
- ※ Avalanche energy specified

SYMBOL:**Maximum ratings (Ta=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _D S	-60	V
Gate-Source Voltage	V _G S	±20	
Continuous Drain Current	I _D	-12	A
Pulsed Diode Current	I _D M	-30	
Power Dissipation	P _D	50	W
Thermal Resistance from Junction to Ambient (t≤10s)	R _{θJA}	65	°C/W
Repetitive avalanche energy L=0.1mH	E _{AR}	20	mJ
Avalanche Current	I _A R	22	A
Operating Junction	T _J	175	°C
Storage Temperature	T _{STG}	-55~+175	



MOSFET ELECTRICAL CHARACTERISTICS

Static Electrical Characteristics (Ta = 25 °C Unless Otherwise Noted)

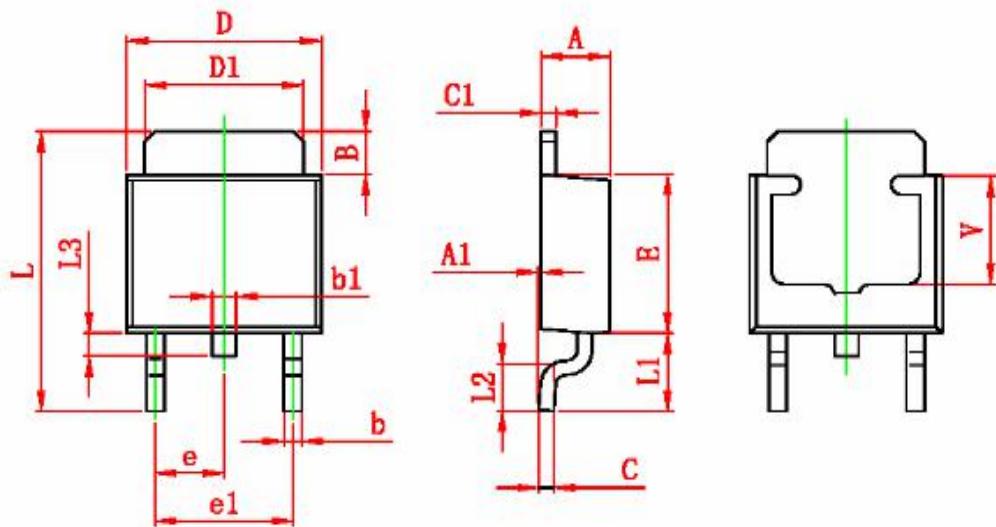
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-source breakdown voltage	V(BR)DSS	VGS = 0V, ID = -250µA	-60			V
Gate-source threshold voltage	VGS(th)	VDS = VGS, ID = -250µA	-1		-3	V
Gate-source leakage	IGSS	VDS = 0V, VGS = ±20V			±100	nA
Zero gate voltage drain current	IDSS	VDS = -50V, VGS = 0V			-1	µA
Drain-source on-state resistancea	RDS(on)	VGS = -10V, ID = -6A		92	115	mΩ
	RDS(on)	VGS = -4.5V, ID = -6A		115	150	mΩ
Forward transconductancea	gfs	VDS = -5V, ID = -12A		13		S
Diode forward voltage	VSD	IS = -1A, VGS=0V		-0.8	-1.2	V
Dynamic						
Input capacitance	Ciss	VDS = -30V, VGS = 0V, f=1MHz		987		pF
Output capacitance	Coss			114		pF
Reverse transfer capacitanceb	Crss			46		pF
Total gate charge	Qg	VDS = -30V, VGS = -10V, ID = -12A		16		nC
Gate-source charge	Qgs			7.5		nC
Gate-drain charge	Qgd			3.5		nC
Gate resistance	Rg	f=1MHz		10		Ω
Switchingb						
Turn-on delay time	td(on)	VDD= -30V RL= 2.5Ω, ID = -12A, VGEN= -10V, Rg = 3.5Ω		9		ns
Rise time	tr			10		ns
Turn-off delay time	td(off)			25		ns
Fall time	tf			11		ns
Drain-Source Diode Characteristics						
Reverse Recovery Time	trr	IF= -12A, dI/dt=100A/s		28		ns
Reverse Recovery Charge	Qrr	IF= -12A, dI/dt=100A/s		30		nC

Note :

- 1.The power dissipation P DSM and current rating IDSM are based on TJ(MAX)=150°C, using $t \leq 10s$ junction-to-ambient thermal resistance.
- 2.The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.
3. Repetitive rating, pulse width limited by junction temperature TJ(MAX)=175°C..
- 4.The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.



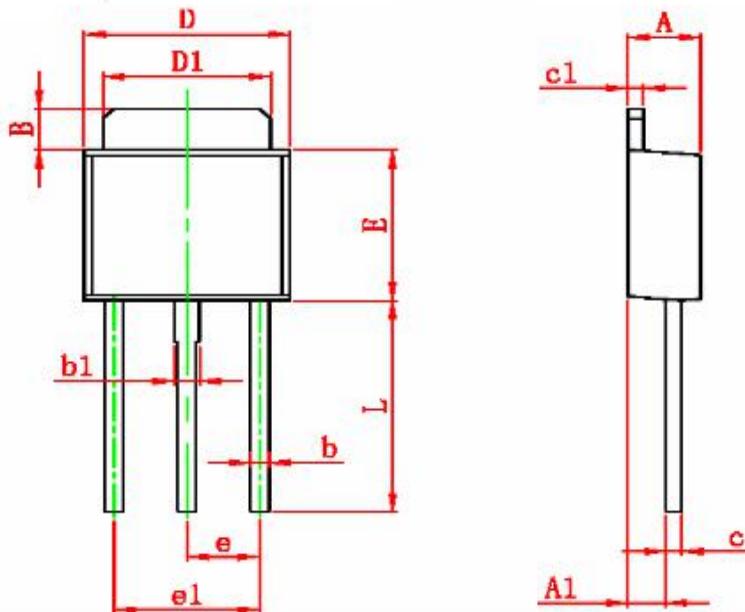
PACKAGE OUTLINE DIMENSIONS :



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP		0.091 TYP	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.350	0.650	0.014	0.026
V	3.80 REF		0.150 REF	



PACKAGE OUTLINE DIMENSIONS :



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.200	2.400	0.087	0.094
A1	1.020	1.270	0.040	0.050
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP		0.091 TYP	
e1	4.500	4.700	0.177	0.185
L	7.500	7.900	0.295	0.311